

# MA4X159AG

## Silicon epitaxial planar type

For switching circuits

### ■ Features

- Two isolated elements contained in one package, allowing high-density mounting
- Short reverse recovery time  $t_{rr}$
- Small terminal capacitance  $C_t$

### ■ Package

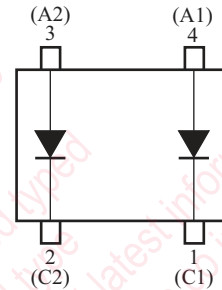
- Code  
Mini4-G3
- Pin Name  
1: Cathode 1  
2: Cathode 2  
3: Anode 2  
4: Anode 1

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	80	V
Maximum peak reverse voltage		$V_{RM}$	80	V
Forward current	Single	$I_F$	100	mA
	Double		75	
Peak forward current	Single	$I_{FM}$	225	mA
	Double		170	
Non-repetitive peak forward surge current *	Single	$I_{FSM}$	500	mA
	Double		375	
Junction temperature		$T_j$	150	$^\circ\text{C}$
Storage temperature		$T_{stg}$	-55 to +150	$^\circ\text{C}$

### ■ Marking Symbol: M1B

### ■ Internal Connection



Note) \*:  $t = 1\text{ s}$

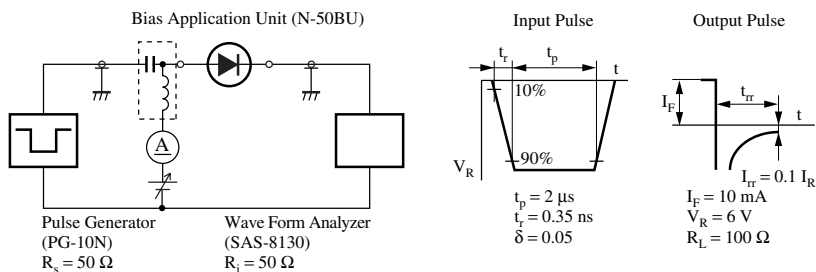
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

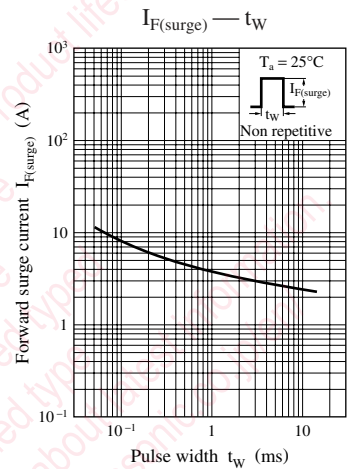
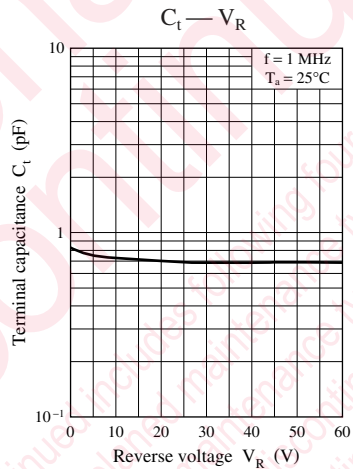
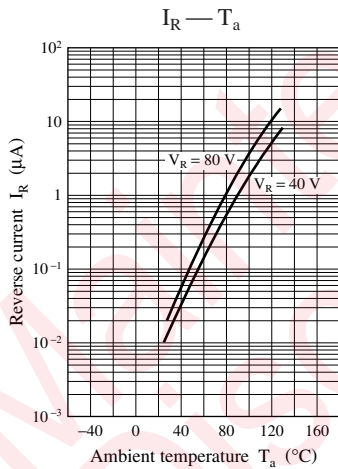
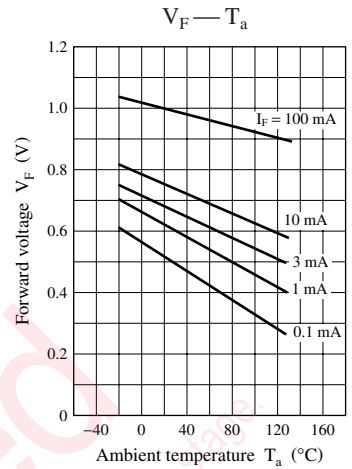
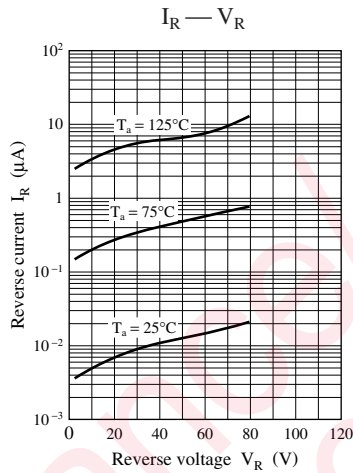
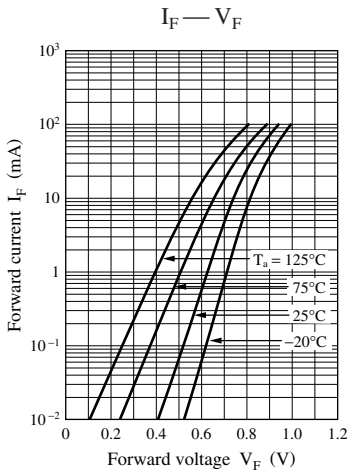
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100\text{ mA}$		0.95	1.20	V
Reverse voltage	$V_R$	$I_R = 100\ \mu\text{A}$	80			V
Reverse current	$I_R$	$V_R = 75\text{ V}$			100	nA
Terminal capacitance	$C_t$	$V_R = 0\text{ V}, f = 1\text{ MHz}$		0.9	2.0	pF
Reverse recovery time *	$t_{rr}$	$I_F = 10\text{ mA}, V_R = 6\text{ V}$ $I_{rr} = 0.1 I_R, R_L = 100\ \Omega$			3	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

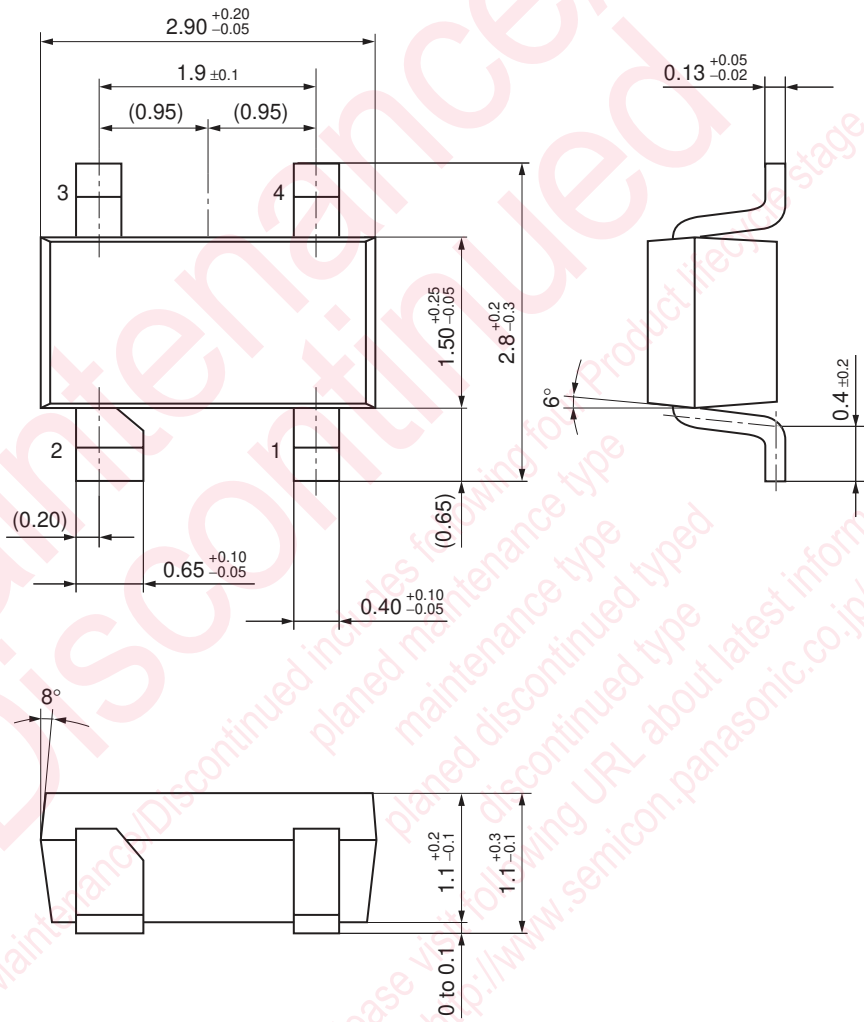
3. \*:  $t_{rr}$  measurement circuit





Mini4-G3

Unit: mm



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